



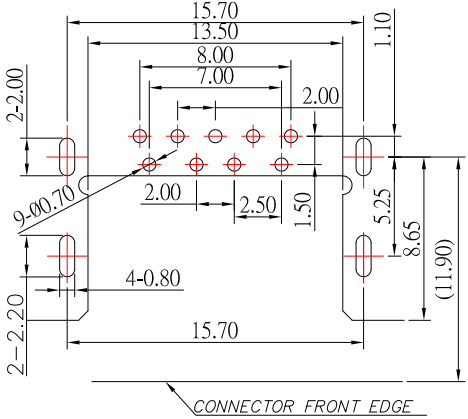
SUA-110E8-30x-S242

鍍層厚度 :

Blank : 1u"

2 : 15u"

3 : 30u"



PCB LAYOUT

NOTE:

1.MATERIAL:

1.1 Housing: LCP

1.2 Contact: Phosphor Bronze

1.3 Shell: SUS

2.Finish:

2.1 Contact: Plated Gold in Mating Area ;

Tin Plated on Solder Balls ;

Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 Current Rate: 1.5 A

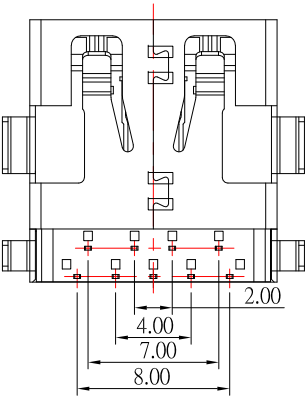
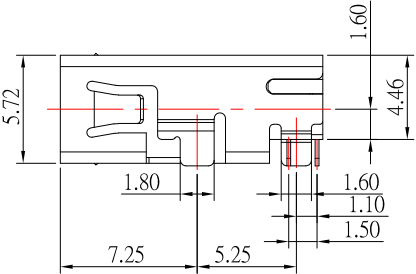
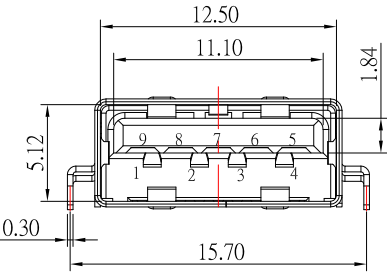
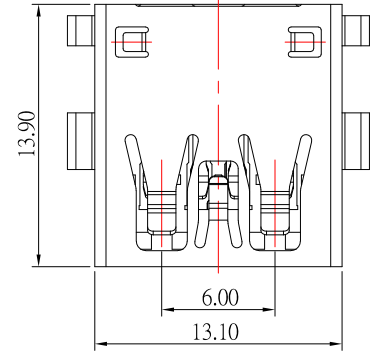
3.2 insulator Resistance:100MΩ Min

3.3 Dielectric Strength: 500V AC

3.4 Contact Resistance: 30mΩ Max

3.5 Insertion Force: 35 N

3.6 Extraction Force: 10 N



Pin #	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°
3RD. ANGEL'S
UNITS
MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	08/13/24	FINISH	MODLE	USB 3.0 A/F 沉板H:4.46 DIP, 無捲邊
CHECKED BY:	DATE	SCALE	DWG NO.	SUA-110E8-30x-S242
Jacky Chen	08/13/24	1 : 1	PART NO.	SUA-110E8-30x-S242
APPROVED BY:	DATE	SHEET NO.	1 of 1	
Tony Kao	08/13/24			